


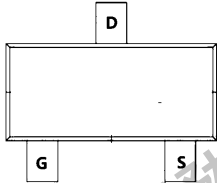
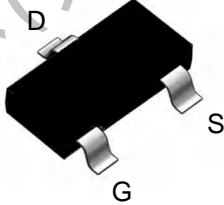
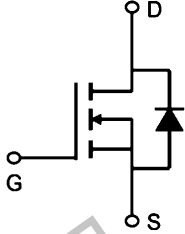


**TM09N03MI**

**N-Channel Enhancement Mosfet**

<p><b>General Description</b></p> <ul style="list-style-type: none"> <li>• Low R<sub>DS(ON)</sub></li> <li>• RoHS and Halogen-Free Compliant</li> </ul> <p><b>Applications</b></p> <ul style="list-style-type: none"> <li>• Load switch</li> <li>• PWM</li> </ul>	<p><b>General Features</b></p> <p>V<sub>DS</sub> = 30V I<sub>D</sub> =9 A R<sub>DS(ON)</sub> = 9 mΩ(Typ.) @ V<sub>GS</sub>=10V</p> <p>100% UIS Tested 100% R<sub>g</sub> Tested</p> 
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MI:SOT-23-3L

Marking:3012A

**Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	9	A
I <sub>D</sub> @T <sub>A</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	5.8	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	30	A
E <sub>AS</sub>	Single Pulse Avalanche Energy <sup>3</sup>	18	mJ
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	1.5	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 175	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 175	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sup>1</sup>	---	48	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case	---	---	°C/W

# TM09N03MI

# N-Channel Enhancement Mosfet

Electrical Characteristics: ( $T_A=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\ \mu\text{A}$	30	---	---	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=150V, V_{GS}=0V$	---	---	1	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
<b>On Characteristics<sup>3</sup></b>						
$V_{GS(th)}$	GATE-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\ \mu\text{A}$	0.9	1.2	1.5	V
$R_{DS(on)}$	Static Drain-Source On Resistance <sup>2</sup>	$V_{GS}=10V, I_D=8A$	---	9	10	$\text{m}\Omega$
		$V_{GS}=4.5V, I_D=6A$	---	12	18	
$G_{FS}$	Forward Transconductance	$V_{DS}=5V, I_D=8A$	---	24	---	S
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$	---	940	1316	$\text{pF}$
$C_{oss}$	Output Capacitance		---	131	183	
$C_{rss}$	Reverse Transfer Capacitance		---	109	153	
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=15V$ $R_{GEN}=1.5\ \Omega, V_{GS}=10V$ $I_D=8A$	---	4.2	8.4	ns
$t_r$	Rise Time		---	8.2	15	ns
$t_{d(off)}$	Turn-Off Delay Time		---	31	62	ns
$t_f$	Fall Time		---	4	8	ns
$Q_g$	Total Gate Charge	$V_{GS}=4.5V, V_{DS}=15V,$ $I_D=8A$	---	9.63	13.5	nC
$Q_{gs}$	Gate-Source Charge		---	3.88	5.4	nC
$Q_{gd}$	Gate-Drain "Miller" Charge		---	3.44	4.8	nC
<b>Drain-Source Diode Characteristics</b>						
$V_{SD}$	Source-Drain Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V
$I_S$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0V$	---	---	9	A
$I_{SM}$	Pulsed Source Current <sup>2,5</sup>		---	---	30	
$T_{rr}$	Body Diode Reverse Recovery Time	$I_F=8A,$ $di/dt=100A/\mu\text{s}, T_J=25^\circ\text{C}$	---	8	---	Ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		---	2.9	---	Nc

**Notes:**

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=22A$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

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N-Channel Enhancement Mosfet

Typical Characteristics:

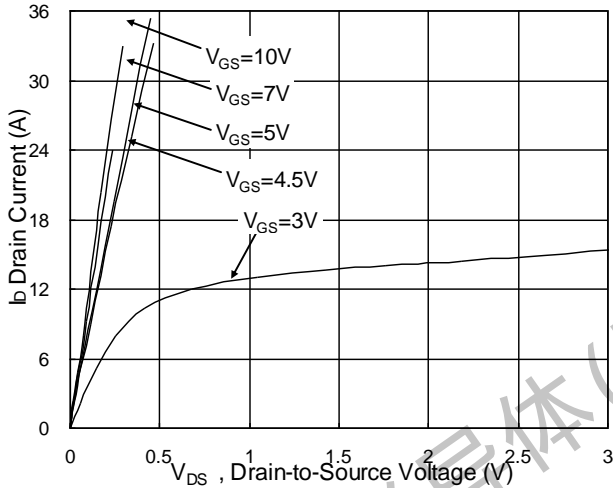


Fig.1 Typical Output Characteristics

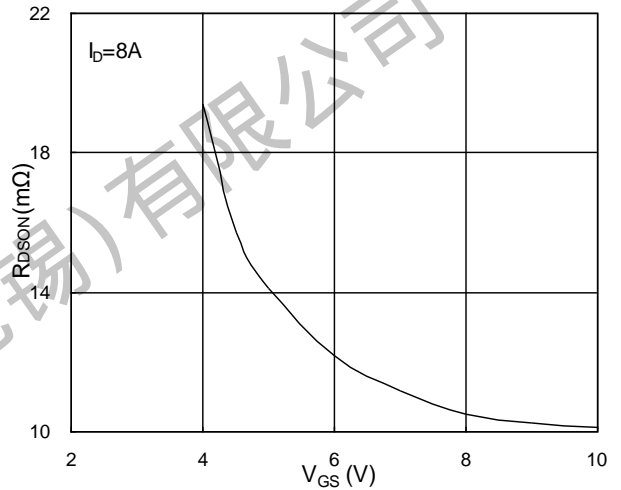


Fig.2 On-Resistance vs. G-S Voltage

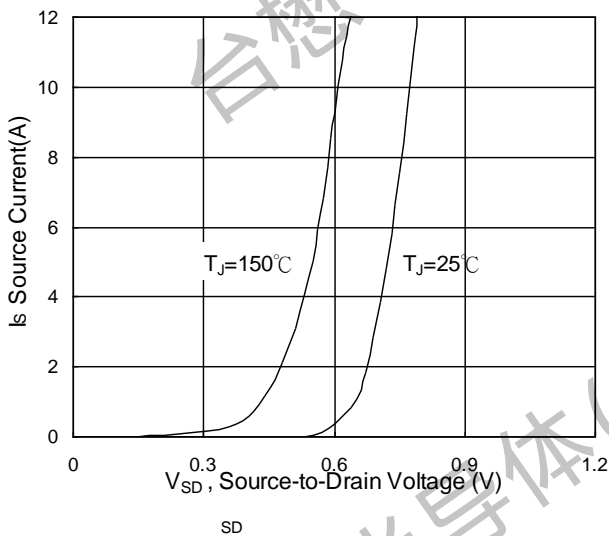


Fig.3 Forward Characteristics of Reverse

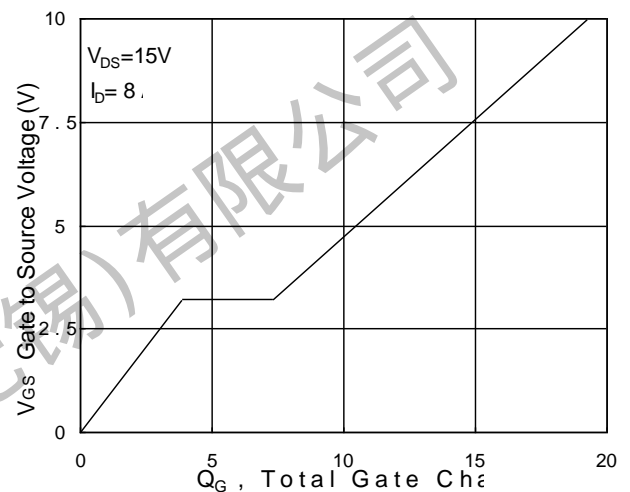
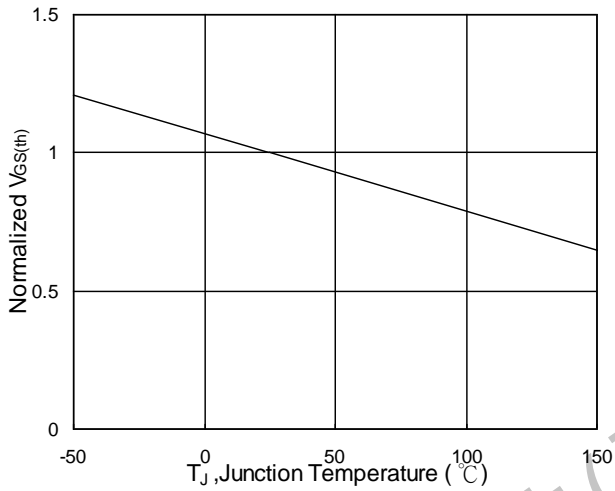


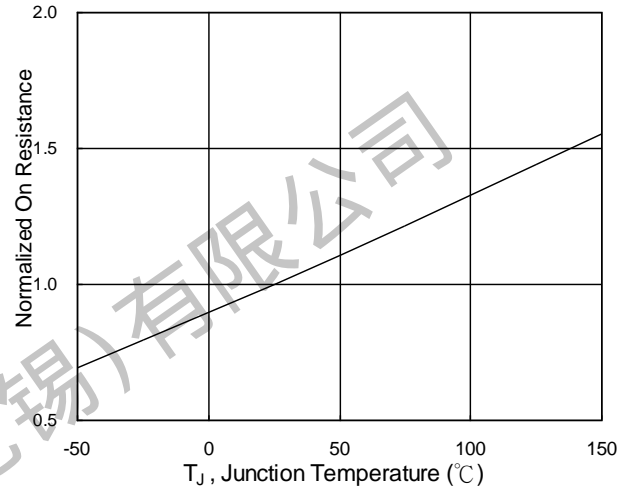
Fig.4 Gate-Charge Characteristics

**TM09N03MI**

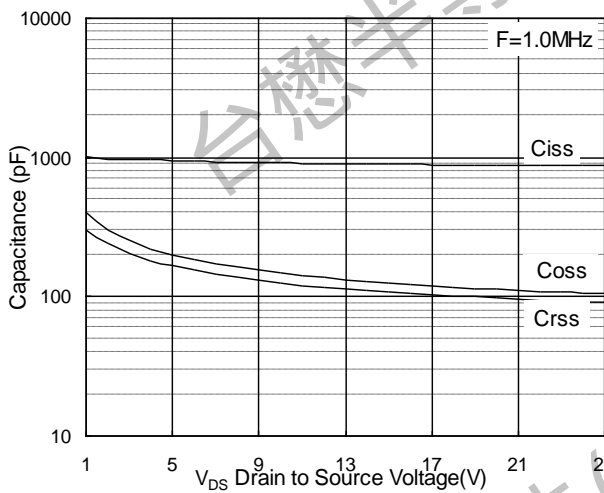
**N-Channel Enhancement Mosfet**



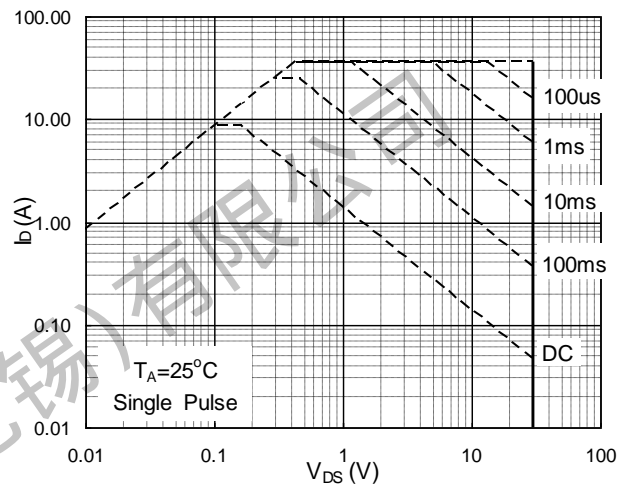
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



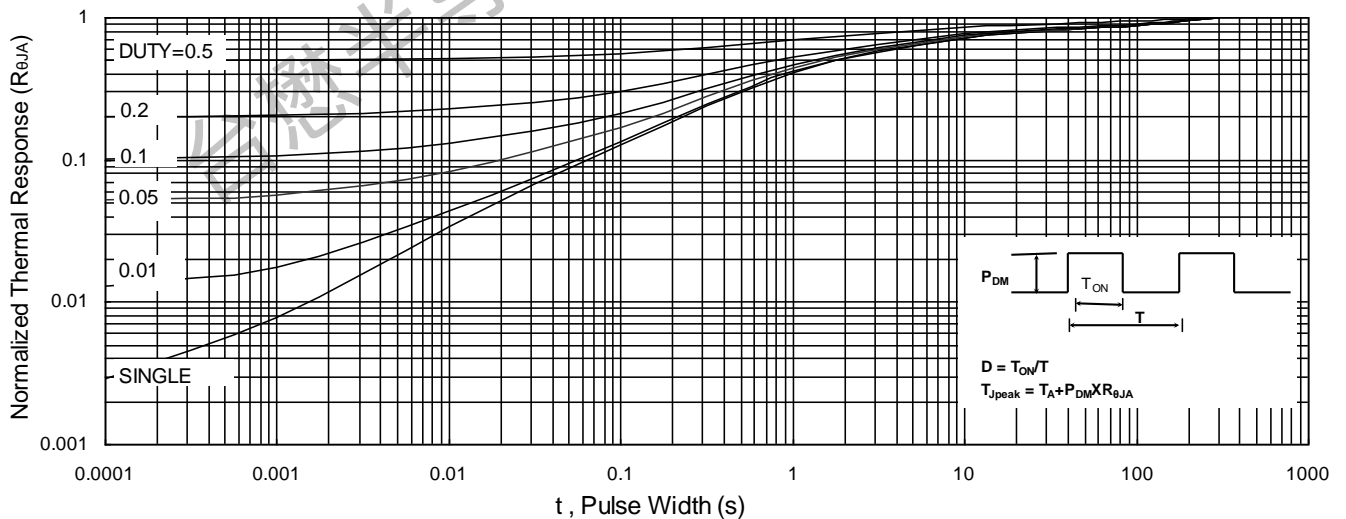
**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**



**Fig.7 Capacitance**



**Fig.8 Safe Operating Area**



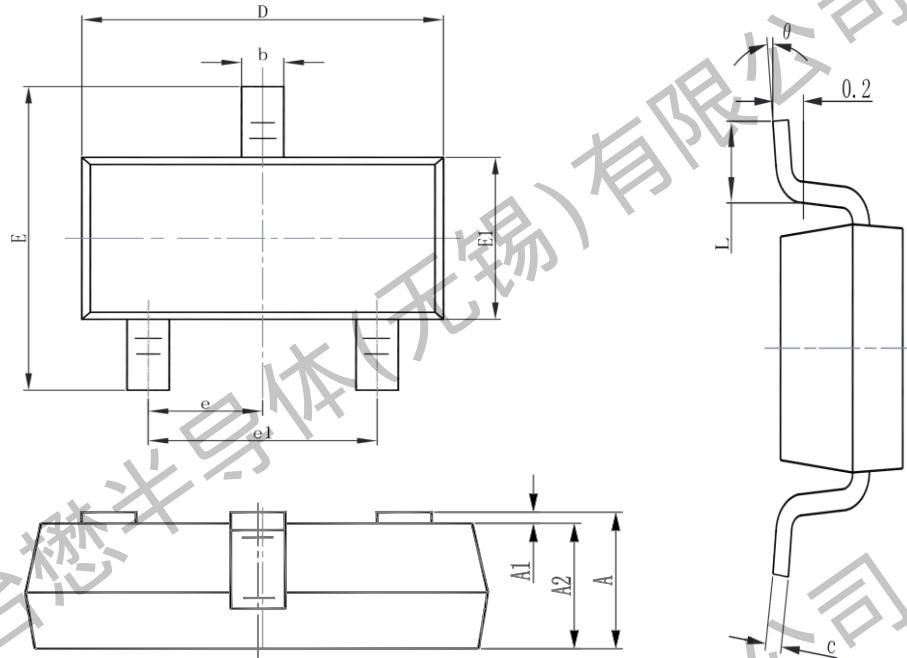
**Fig.9 Normalized Maximum Transient Thermal Impedance**



TM09N03MI

N-Channel Enhancement Mosfet

Package Mechanical Data:SOT-23-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

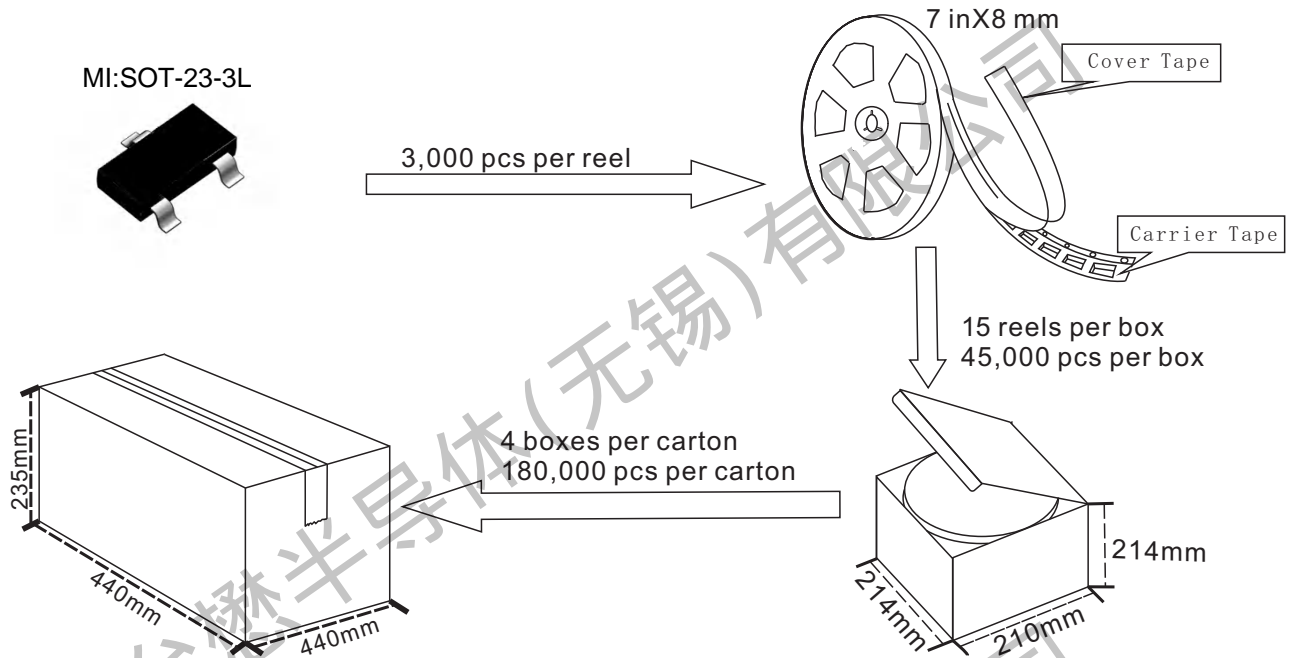


**TM09N03MI**

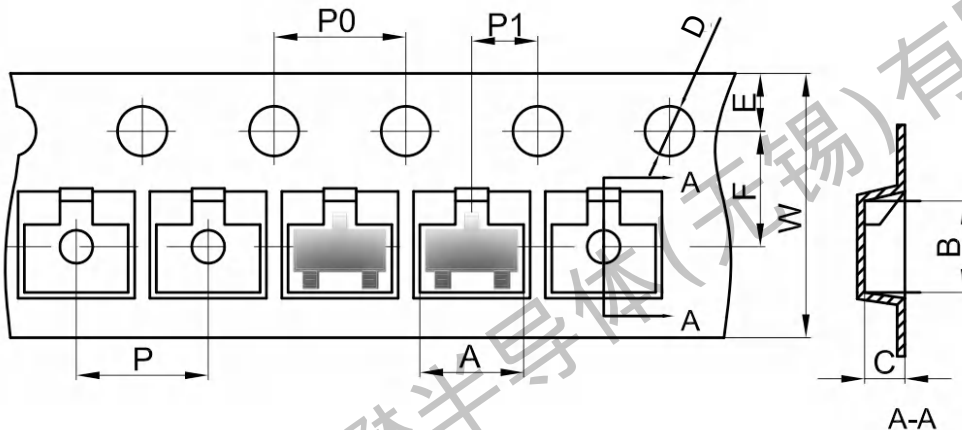
**N-Channel Enhancement Mosfet**

**SOT-23-3L Packing**

1. The method of packaging and dimension are shown as below figure. (Dimension in mm)



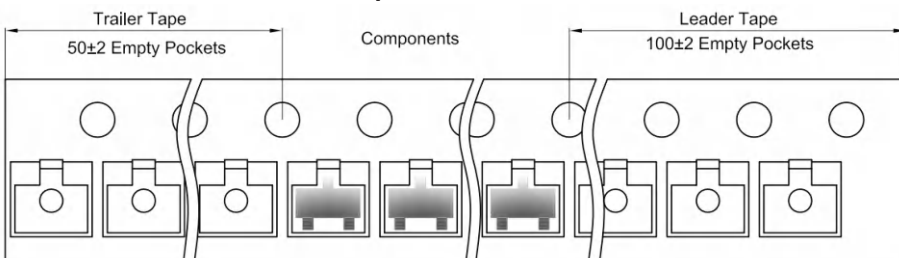
**SOT-23-3L Embossed Carrier Tape**



Dimensions are in millimeter

Pkg type	A	B	C	D	E	F	P0	P	P1	W
SOT-23-3L	3.15	2.77	1.22	Ø1.50	1.75	3.50	4.00	4.00	2.00	8.00

**SOT-23-3L Tape Leader and Trailer**





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Revision history:

Date	Rev	Description	Page
2023.08.03	23.08	Original	